EB13C5J2H-40.000M



Nominal Frequency

40.000MHz

Logic Control / Additional Output Tri-State

Series -RoHS Compliant (Pb-free) Low Current 3.3V 4 Pad 3.2mm x 5mm Ceramic SMD LVCMOS Oscillator

Frequency Tolerance/Stability ±25ppm over -40°C to +85°C

Duty Cycle -50 ±5%

EB13C5 J 2 H -40.000M

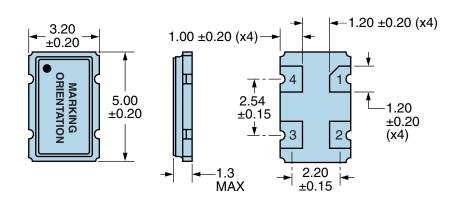
| ELECTRICAL SPECIFICA | ΓΙΟΝS |
|---------------------------------------|---|
| Nominal Frequency | 40.000MHz |
| Frequency Tolerance/Stability | ±25ppm over -40°C to +85°C (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Ouput Load Change, First Year Aging at 25°C, Shock, and Vibration) |
| Supply Voltage | 3.3Vdc ±10% |
| Input Current | 5mA Maximum |
| Output Voltage Logic High (Voh) | 90% of Vdd Minimum |
| Input Current Logic High (Ioh) | -1.6mA |
| Output Voltage Logic Low (Vol) | 10% of Vdd Maximum |
| Input Current Logic Low (IoI) | +1.6mA |
| Rise/Fall Time | 4nSec Maximum (Measured at 20% to 80% of waveform) |
| Duty Cycle | 50 ±5% (Measured at 50% of waveform) |
| Load Drive Capability | 15pF Maximum |
| Output Logic Type | CMOS |
| Logic Control / Additional Output | Tri-State |
| Tri-State Input Voltage (Vih and Vil) | 90% of Vdd Minimum or No Connect to Enable Output, 10% of Vdd Maximum to Disable Output (High Impedance) |
| Standby Current | 10µA Maximum (Disabled Output: High Impedance) |
| One Sigma Clock Period Jitter | 25pSec Maximum |
| Start Up Time | 10 mSec Maximum |
| Storage Temperature Range | -55°C to +125°C |

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

| Fine Leak Test | MIL-STD-883, Method 1014, Condition A |
|------------------------------|---------------------------------------|
| Gross Leak Test | MIL-STD-883, Method 1014, Condition C |
| Mechanical Shock | MIL-STD-202, Method 213, Condition C |
| Resistance to Soldering Heat | MIL-STD-202, Method 210 |
| Resistance to Solvents | MIL-STD-202, Method 215 |
| Solderability | MIL-STD-883, Method 2003 |
| Temperature Cycling | MIL-STD-883, MEthod 1010 |
| Vibration | MIL-STD-883, Method 2007, Condition A |

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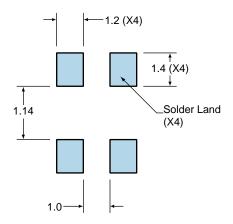
MECHANICAL DIMENSIONS (all dimensions in millimeters)



| PIN | CONNECTION |
|-----------|---|
| 1 | Tri-State |
| 2 | Ground |
| 3 | Output |
| 4 | Supply Voltage |
| | |
| | |
| LINE | MARKING |
| LINE 1 | MARKING E40.000 E=Ecliptek Designator |

Suggested Solder Pad Layout

All Dimensions in Millimeters



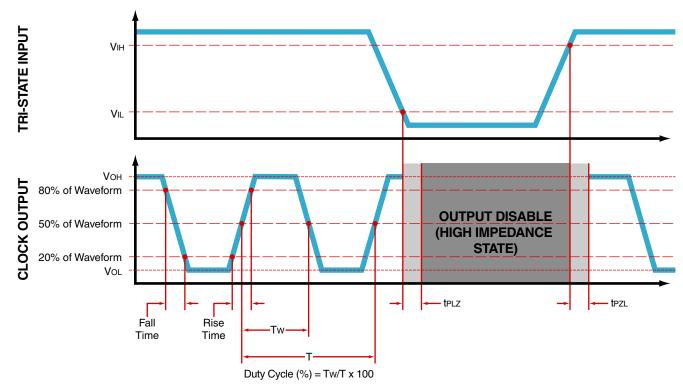
All Tolerances are ±0.1



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OUTPUT WAVEFORM & TIMING DIAGRAM



Test Circuit for CMOS Output



Note 1: An external 0.1μ F low frequency tantalum bypass capacitor in parallel with a 0.01μ F high frequency ceramic bypass capacitor close to the package ground and V_{DD} pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value \dot{C}_L includes sum of all probe and fixture capacitance.



Recommended Solder Reflow Methods



High Temperature Infrared/Convection

EB13C5J2H-40.000M

| T_s MAX to T_L (Ramp-up Rate) | 3°C/second Maximum |
|---|--------------------------------------|
| Preheat | |
| - Temperature Minimum (T _s MIN) | 150°C |
| - Temperature Typical (T _s TYP) | 175°C |
| - Temperature Maximum (T _s MAX) | 200°C |
| - Time (t _s MIN) | 60 - 180 Seconds |
| Ramp-up Rate (T⊾ to T _P) | 3°C/second Maximum |
| Time Maintained Above: | |
| - Temperature (T∟) | 217°C |
| - Time (t∟) | 60 - 150 Seconds |
| Peak Temperature (T _P) | 260°C Maximum for 10 Seconds Maximum |
| Target Peak Temperature (T _P Target) | 250°C +0/-5°C |
| Time within 5°C of actual peak (t_p) | 20 - 40 seconds |
| Ramp-down Rate | 6°C/second Maximum |
| Time 25°C to Peak Temperature (t) | 8 minutes Maximum |
| Moisture Sensitivity Level | Level 1 |



Recommended Solder Reflow Methods

EB13C5J2H-40.000M



Low Temperature Infrared/Convection 240°C

| T _s MAX to T _L (Ramp-up Rate) | 5°C/second Maximum |
|---|--|
| Preheat | |
| - Temperature Minimum (Ts MIN) | N/A |
| - Temperature Typical (T _s TYP) | 150°C |
| - Temperature Maximum (T _s MAX) | N/A |
| - Time (t _s MIN) | 60 - 120 Seconds |
| Ramp-up Rate (T _L to T _P) | 5°C/second Maximum |
| Time Maintained Above: | |
| - Temperature (T∟) | 150°C |
| - Time (t∟) | 200 Seconds Maximum |
| Peak Temperature (T _P) | 240°C Maximum |
| Target Peak Temperature (T _P Target) | 240°C Maximum 1 Time / 230°C Maximum 2 Times |
| Time within 5°C of actual peak (t _p) | 10 seconds Maximum 2 Times / 80 seconds Maximum 1 Time |
| Ramp-down Rate | 5°C/second Maximum |
| Time 25°C to Peak Temperature (t) | N/A |
| Moisture Sensitivity Level | Level 1 |

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.